

### High Performance Chuck for your needs

In the probing industry, the demand for improved test performance is critical. The ISO-CHUCK solution can upgrade your existing probe system with an advanced design with lower capacitance, low current leakage, and provide an excellent solution for high voltage test environments. The power of the ISO-CHUCK design is in its nonconductive, lightweight material. The applied metallization to this fixture in specific areas supplies surface connection and isolated shielding components resulting in advanced performance for the probing industry.



ISO-CHUCK for Electroglas 2001 with dual BNC connectors

With the versatility of a multilayered PC board, and the support of a metal wafer chuck, the ISO-CHUCK offers an excellent opportunity to improve the test environment with today's demanding performance requirements.



materials that APT has chosen for the ISO-CHUCK design is Ultem. This material has solid mechanical & light weight properties, with excellent electrical properties, and a dielectric constant of 3.15 with a volume resistivity of 1.0x10<sup>17</sup>.

One of the many

Shown with Kelvin design for Electroglas 2001 with wafer transport and lift pin configuration

# Designs for complex OEM replacements Electroglas, KLA, TEL & all analytical probers

The wafer chuck capacitance in the 4", 6" and 8" test environments was a controllable factor. With the current advancements in the 300mm wafers, this is no longer a minor factor to overcome. The low density material of the ISO-CHUCK design, compared to its 300mm metal counterparts, provides advantages in mechanical repeatability due to the lower mass. The low dielectric constant provides very low chuck capacitance in the triaxial versions of less than 200pF, and less than 10pF with a driven quard!

- Low inertia for high speed testing
- Low leakage between conductors for low current testing
- Low capacitance triax designs
- Low contact resistance conductors, with choice of plating materials
- Coaxial, triaxial, Kelvin, & high voltage models available
- Models for 4", 6", 8" and now 300mm (12")

ISO-CHUCK is trade name and is a patented design protected by US patent # 6,236,221,B1



Typical leakage results using Agilent 4156C Precision Semiconductor Parameter Analyzer.

#### **CONFIGURATIONS & MATERIALS**

- Ultem 1000 is one of several materials available for the ISO-CHUCK series of wafer chucks. Contact American Probe & Technologies for details on the material and configuration which will result in superior electrical or mechanical properties for your custom application.
- American Probe & Technologies has built its success on products that are high quality, and tested at our facility to meet or exceed the specifications requested. APT has a complete test and measurement laboratory and can provide a certificate of compliance.
- APT offers a complete line of low current probes and test accessories to provide a turnkey system solution for your analytical test requirements.
- For a listing of other superior products offered by American Probe & Technologies', please refer to our web site at www.americanprobe.com

**Electrical Properties:** 

## **ISO-CHUCK INFORMATION USING ULTEM**

### **Mechanical Properties:**

Materials:			Dielectric Strength:	831 v	olt/mil
Base:	Ultem 1000		Volume Resistivity	Volume Resistivity 1.0x1	
Base Plating:	Copper (0.003"-0.005")		Dielectric Constant	3.15@1kHz:	
Finish Plating	Gold (type II) (0.0015")		<b>Dissipation Factor</b>	0.0013@1kHz:	
	with nickel base coat (0.002")				
			Current Leakage	< 50	fA @ 100 VDC
Specifications of Ultem:			Settle Time	<15 :	seconds (typical)
Specific Gravity:		1.27	Contact Resistance	<1 m	illi-ohm (typical)
Tensile Strength	ו:	15,200 psi @73°C			
Tensile Modulus: 430,000 psi			Capacitance @ 30 VDC (top to guard/ground):		
Flexural Strength:		21,000 psi	Typical configurations:		
Hardness, Rockwell:		M105 @73°C	6" with 0.5" thickness:		< 50pF
Water absorption, Immersion (24 hours): 0.25%			6" with 0.75" thickness: < 35pF		< 35pF
Deflection Temp	erature:	264 psi@392°F			
Excellent chemical resistance to acid/base			8" with 0.5" thickness:		< 85pF
			8" with 0.75" thicknes	S:	< 60pF
Wafer Chuck Fla	tness:	within 0.0008"			
√afer Chuck Parallelism: within 0.001"		within 0.001"	12" with 0.75" thickness:		< 120pF
Deflection: TBD		12" with 1.0" thickness:		< 95pF	

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The information contained in this document is preliminary and may change without notice.